

## FOR IMMEDIATE RELEASE

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## AEHR TEST SYSTEMS ANNOUNCES PARTICIPATION IN INTERNATIONAL TEST CONFERENCE

Fremont, CA (November 7, 2012) - Aehr Test Systems (Nasdaq: AEHR), a worldwide supplier of semiconductor test and burn-in equipment is participating this week in the International Test Conference in Anaheim, CA. Aehr is showcasing its FOX<sup>TM</sup> full-wafer test system and its ABTS<sup>TM</sup> burn-in and test system for packaged parts in the exhibition from November 6-8. Aehr is demonstrating the latest version of the ABTS system, which features a per-pin architecture for increased flexibility in testing state-of-the-art logic devices.

In addition, Gayn Erickson, CEO and President of Aehr Test, participated in the Entrepreneurship in Test CEO Panel Discussion on Monday, November 5. The panel discussed the reasons behind the success of several companies in the Automatic Test Equipment (ATE) industry and the opportunities produced by changes in integrated circuits for innovation today, focusing on simplifying test development and lowering the cost of test.

The FOX-1 full wafer parallel test system has the capability to test thousands of die in a single touchdown, thus providing a cost-effective solution for devices with long test times such as flash and microcontrollers with embedded flash.

The FOX-15 Burn-in and Test System provides cost effective test and high reliability burn-in of up to 15 wafers in parallel for applications such as automotive ICs, DRAMs, flash memory, sensors and VCSELs (laser diodes). The FOX-15 system performs burn-in of bare die at the wafer level so that Known Good Die (KGD) can be produced for stacked die and through silicon via (TSV) applications.

The ABTS family of products is based on a new hardware and software architecture that is designed to address not only today's devices, but also future devices for many years to come. It can test and burn-in both logic and memory devices, including resources for high pin-count devices and configurations for high-power and low-power applications. The ABTS system can be configured with up to 72 burn-in boards with up to 320 I/O channels each and 32M of test vector memory per channel. The ABTS system is optimized for use with the Sensata iSocket\* Thermal Management Technology, which provides a scalable cost-effective solution using individual device temperature control for ICs up to 75 watts or more. Individual temperature

control enables high-power devices with a broad range of power dissipation to be burned-in simultaneously in a single burn-in chamber while maintaining a precise device temperature. The ABTS system also uses N+1 redundancy technology for many key components in the system to maximize system uptime.

\*iSocket is a trademark of Sensata Technologies, Inc.

## **About Aehr Test Systems**

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS and FOX families of test and burn-in systems and the DiePak® carrier. The ABTS system is used in production and qualification testing of packaged parts for both low-power and high-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at www.aehr.com.

## **Safe Harbor Statement**

This release contains forward-looking statements that involve risks and uncertainties relating to projections regarding revenues, net sales and customer demand and acceptance of Aehr Test's products. Actual results may vary from projected results. These risks and uncertainties include without limitation, world economic conditions, the state of the semiconductor equipment market, the Company's ability to maintain sufficient cash to support operations, acceptance by customers of Aehr Test's technologies, acceptance by customers of the systems shipped upon receipt of a purchase order, the ability of new products to meet customer needs or perform as described and the Company's ability to successfully market a wafer-level test and burn-in system. See Aehr Test's recent 10-K, 10-Q and other reports from time to time filed with the U.S. Securities and Exchange Commission for a more detailed description of the risks facing our business. The Company disclaims any obligation to update information contained in any forward-looking statement to reflect events or circumstances occurring after the date of this press release.

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